

Hello, and welcome to this presentation of the STM32F7 power controller. It covers the efficient power management and all STM32F7 power modes.

## Key features

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- Enhanced dynamic power with freerunning clocks gating
- Triple power domains including 2 dedicated ones for USB and SD-MMC/standard serial interfaces
- Independent MIPI DSI PHY supply
- Battery backup mode with RTC, backup registers and backup SRAM

### Application benefits

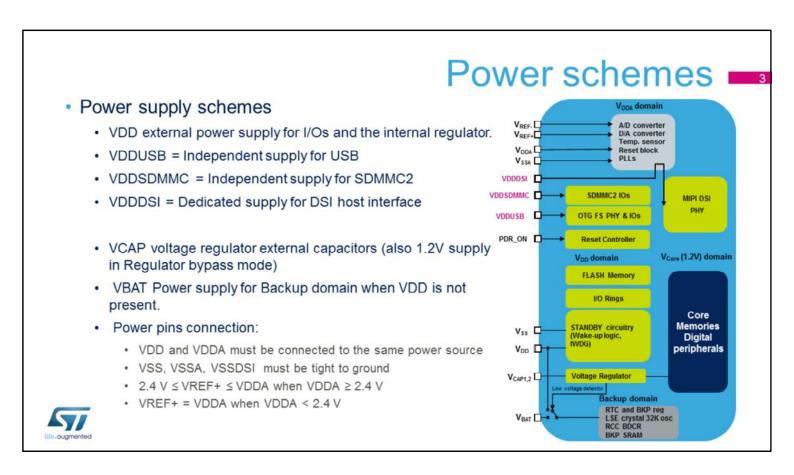
- High performance
- → CoreMark score = 1000 @ 200 MHz \*\*
- Enhanced power efficiency
- → 425 µA/MHz\*

\*\* Typ @VDD=3.3V @25°C CoreMark execution from Flash, peripherals off



The STM32F7 has several key features related to power management:

- Efficient dynamic consumption with free running clocks gating when needed. This allows to go down to 425  $\mu$ A/MHz, executing from Flash memory,
- Independent power supplies, allowing to reduce MCU power consumption while some peripherals are supplied at higher voltages,
- A battery backup domain, called  $V_{\text{BAT}}\,,$  including the RTC and certain backup registers.



The STM32F7 has several power supplies.

The main power supply is VDD, and supplies almost all the I/Os except those mapped on dedicated supplies. In addition, VDD supplies the Standby circuitry which includes the wakeup logic and independent watchdog. VDD supplies voltage regulators which provide the  $V_{CORE}$  supply.  $V_{CORE}$  supplies most of the digital peripherals and the SRAMs. The Flash memory is supplied by both  $V_{CORE}$  and VDD.

 $V_{\text{CAP1}}$  and  $V_{\text{CAP2}}$  pins have to be connected to external capacitors in Regulator-ON mode, the exact value is specified in the datasheet.

In Regulator bypass mode the  $V_{CORE}$  supply can be provided externally on  $V_{CAP1}$  and  $V_{CAP2}$  pins, , the value for the  $V_{CORE}$  specified in the datasheet  $V_{CAPDSI}$  pin have to be connected to external capacitors when the DSI regulator is available, the exact value is

specified in the datasheet.

Internal regulators providing VCORE can also be BYPASSED and 1.2 V supply is provided by the VCAP pin in Regulator-OFF mode. Regulator ON/OFF mode is only available on packages with a BYPASS\_REG pin.

STM32F7 microcontrollers feature several independent supplies for peripherals:

- VDDA for the analog peripherals, device PLLs and internal reset block. VDD and VDDA must be connected to the same source.
- VDDUSB for the USB transceiver.
- VDDSDMMC supplies 6 IOs used for SD card communication, SDMMC2 clock, command and 4 data pins.
- The VDDDSI pin provides the DSI peripheral voltage supply.

The VDDSDMMC and VDDDSI pins are available only on some STM32F7 devices.

The V<sub>REF</sub>+ pin provides the reference voltage to the analog-to-digital and to digital-to-analog converters.

A backup battery can be connected to  $V_{\text{BAT}}$  pin to supply the backup domain.

### Power schemes

#### Optimized power and performance thanks to independent power supplies

- VDD from 1.8 to 3.6 V: External power supply for I/Os and the internal regulator (down to 1.7 V when internal reset is OFF and device operates in the 0 to 70°C temperature range)
- VDDA from 1.8 to 3.6 V: External analog power supplies for ADC, DAC, Reset blocks, RCs and PLLs
- VDDUSB from 3 to 3.6 V for USB transceivers
- VDDSDMMC from 1.8 to 3.6V for pins PG[12:9], PD[7,6] :
  - · Available starting from 144-pin packages
  - · With SDMMC2 and SPI1 function.
- VBAT from 1.65 to 3.6 V: power supply for Backup domain when VDD is not present



The main power supply VDD ensures full feature operation in all power modes from 1.7 up to 3.6 V, allowing the microcontroller to be supplied by an external 1.8 V regulator. Device functionality is guaranteed down to 1.7 V when the internal reset is OFF.

The analog power supply VDDA must be connected to VDD. When the analog-to-digital-converter is used, VDDA voltage has an impact on its performance. VDDA must be greater than 2.4 V for maximum ADC performance.

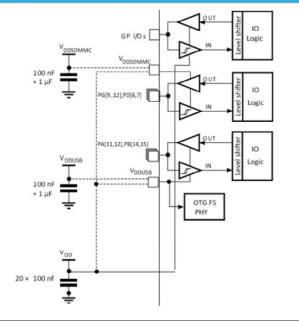
The USB power supply (VDDUSB) can be connected to any voltage other than VDD. When the USB is used, VDDUSB must be greater than 3V. GPIO pins PA11, PA12, PB14 and PB15 are supplied by VDDUSB.
6 I/Os corresponding to PF9 to PG12, PD6 and PD7 are supplied by VDDSDMMC independently from VDD. Several functions are available on these I/Os: SDMMC2

in 4-bit mode, SPI1, I2S1. VDDSDMMC is available starting with packages that have at least 144 pins. A backup domain is supplied by VBAT, which must be greater than 1.65 V. The backup domain contains the RTC, the 32.768-kHz LSE external oscillator and the 128-byte backup registers.

### Power schemes

### Independent power supplies for USB and SDMMC2

- V<sub>DDSDMMC</sub> SDMMC2 supply voltage
  - Supply voltage for pins PG[12:9] and PD[7,6] pins.
  - Ranging from 1.7 to 3.6 V
  - It can be different from VDD
- V<sub>DDUSB</sub> USB supply voltage
  - Supply voltage for pins PA11, PA12, PB14 and PB15 and also for USB transceiver from 3 to 3.6 V when USB is used.





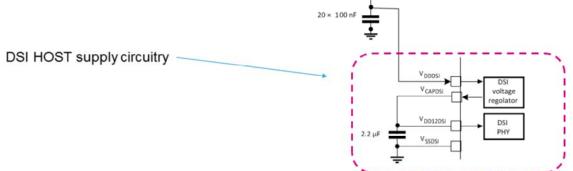
VDDSDMMC is available only on some STM32F7 devices. It allows several IOs and functions (SDMMC2 in 4-bit mode, SPI1 or I2S1) to be used independently from VDD. 4 I/Os corresponding to PA11, PA12, PB14 and PB15 are supplied by VDDUSB independently from VDD. VDDUSB is used mainly as a USB transceiver supply when VDD is below 3V. Several functions are available on these I/Os: USART1, USART4, SPI2 or I2S2.

### Power schemes •

#### Independent supplies for DSI Host

- VDDDSI: From 1.7 to 3.6 V supply voltage for DSI Host regulator
- VCAPDSI: DSI regulator external capacitor

 VDD12DSI: Typical 1.2 V internal voltage on VDD12DSI for MIPI DSI PHY





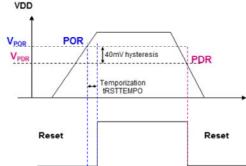
VDDDSI is available only on some STM32F7 packages embedding the DSI Host peripheral.

The VDDDSI pin provides the DSI Host peripheral with a voltage supply ranging from 1.7 up to 3.6V. VCAPDSI is the DSI voltage regulator external capacitor. VDD12DSI is for the MIPI DSI PHY supply, typical input voltage is 1.2V

# Power supply supervisor -

### Power On Reset (POR)/Power Down Reset (PDR)

- Integrated POR / PDR circuitry:
  - · The device has an integrated POR/PDR circuitry that allows proper operation starting from/down to 1.8 V.
  - Always ON
- POR and PDR have 40 mV hysteresis





The STM32F7 has an integrated POR/PDR circuitry that allows proper operation starting from 1.8 V. The device remains in Reset mode when VDD/VDDA is below a specified threshold without the need for an external reset circuit.

The hysteresis between Power-ON threshold and Power-OFF threshold is 40mV.

After reaching Power-ON threshold for VDDA and VDD power supplies, the reset line is still kept low for a temporization time and then the reset line is released.

### Power supply supervisor — Internal reset management Internal reset ON: PDR\_ON tied to VDD Internal reset OFF: PDR ON tied to VSS VDD=1.7V VDD=1.7V STM32F7xx STM32F7xx Application Reset Application Reset signal (optional) PDR ON Internal Reset OFF VSS Internal Reset OFF PDR\_ON managed by external VDD $PDR_ON = 0$ power supervisor

The embedded internal reset controller monitors the VDD supply to detect if the supply is present or not and releases the reset signal when the supplied power reaches the threshold of 1.8V.

The internal reset controller can be disabled by connecting PDR\_ON pin to VSS. When disabled it allows STM32 microcontrollers to operate down to 1.7V.

On STM32F7 microcontrollers, no external VDD power supervisor is needed to manage resets when the internal reset is OFF.

# Power supply supervisor

### **Brown Out Reset (BOR)**

- During power-on, the Brown-out reset (BOR) keeps the device under reset until the supply voltage reaches the specified VBOR threshold.
  - · No need for external reset circuit
- BOR has a typical hysteresis of 100 mV
- BOR levels are configurable by option bytes:
  - BOR OFF: 2.1 V at power-on and 1.62 V at power-down
  - BOR LOW (DEFAULT): 2.4 V at power-on and 2.1 V at power-down
  - BOR MEDIUM: 2.7 V at power-on and 2.4 V at power-down
  - BOR HIGH: 3.6 V at power-on and 2.7 V at power-down



In addition to Power-On reset functionality, there is also a user configurable Brownout reset (BOR) unit, which keeps the device under reset until the supply voltage reaches the specified VBOR threshold.

BOR levels are configurable by option bytes:

- BOR OFF
- BOR LOW (DEFAULT)
- BOR MEDIUM
- BOR HIGH

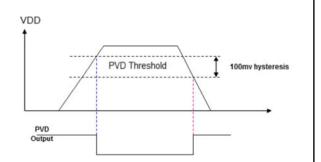
VBOR is configured through device option bytes. By default, BOR is off. 3 programmable VBOR threshold levels can be selected:

- BOR Level 3 (VBOR3). Brownout threshold level 3.
- BOR Level 2 (VBOR2). Brownout threshold level 2.
- BOR Level 1 (VBOR1). Brownout threshold level 1.

For full details about BOR characteristics, refer to the "Electrical characteristics" section in the device datasheet. This function is useful in applications where several devices have different operational voltage range. Depending on the BOR level, the F7 microcontroller will not start until VDD voltage reaches the operational range of all connected devices.

# Programmable Voltage Detector (PVD)

- Programmable Voltage Detector
  - · Enabled by software
  - Monitors the VDD power supply by comparing it to a threshold
  - Threshold configurable from 2.0 to 2.9 V in steps of 100 mV
  - Generates interrupt through EXTI Line16 (if enabled) when VDD < Threshold and/or VDD > Threshold
  - → Can be used to generate a warning message and/or put the MCU into a safe state



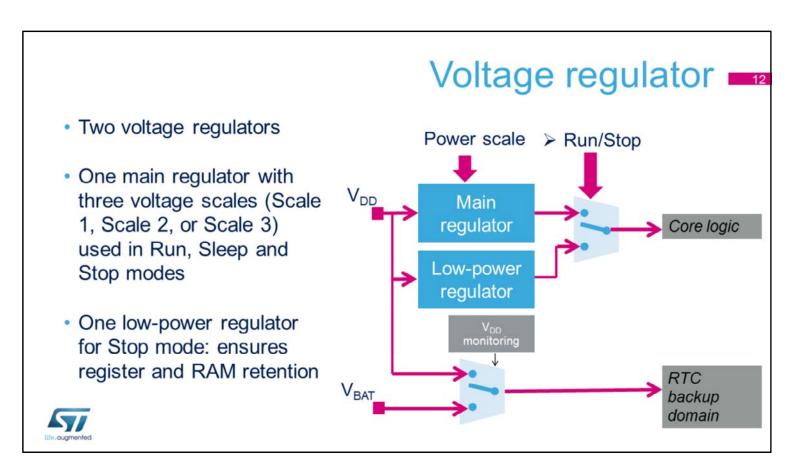


The programmable voltage detector (PVD) is used to monitor the VDD power supply by comparing it to a threshold selected by software. An interrupt can be generated when VDD drops below the PVD threshold and/or when VDD rises above the PVD threshold. PVD is internally connected to EXTI line 16.

Depending on STM32F7 device, PVD interrupt can be connected to Break input of Timer 1 or Timer 8 to put the timer's output signals in a safe configuration.

#### Power supply supervisor Voltage regulator and internal reset modes vs packages Internal reset Internal reset **Regulator ON Regulator OFF Package** ON **OFF** Yes No LQFP100 Yes No LQFP144 LQFP208 WLCSP143 Yes LQFP176. Yes BYPASS REG set Yes BYPASS REG UFBGA176, to VDD Yes PDR\_ON TFBGA216 set to VSS PDR\_ON set to connected to VDD VSS WLCSP180 Two part numbers available

This table describes the Regulator ON/OFF and internal reset ON/OFF availability per package. For a list of available package per STM32F7 line please refer to datasheet.



Two embedded linear voltage regulators supply all the digital circuitries except for the Standby circuitry and the Backup domain.

The regulator output voltage ( $V_{CORE}$ ) can be programmed by software to three different values depending on the performance and the power consumption requirements. This is called Dynamic Voltage Scaling.

Depending on the application mode, V<sub>CORE</sub> is provided either by the main voltage regulator for Run, Sleep and Stop modes, or by the low-power regulator for Stop mode to optimize power consumption. The regulators are OFF in Standby mode. SRAMs and peripheral are powered-down in Standby. They must be reinitialized after exiting from this mode.

### Backup domain RTC Backup domain RTC unit and 4 Kbytes of Backup RAM power switch V<sub>BAT</sub> $\varphi$ Protection to avoid unwanted write accesses to RTC & Backup SRAM V<sub>DD</sub> I

- LVR for the backup RAM
  - · Switch off option
- VBAT independent voltage supply
  - Automatic switch-over to VBAT when VDD goes below PDR level
    - · No current sunk on VBAT when VDD present
    - · Prevent from power line down



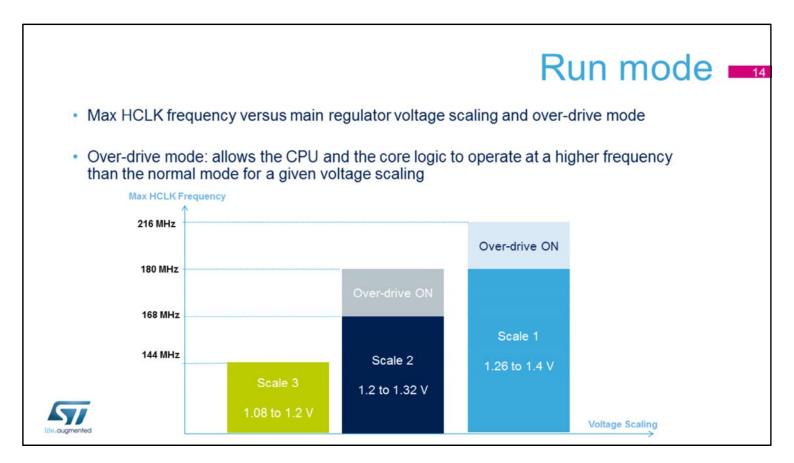
The backup domain contains essentially the following blocks:

- The RTC unit and 128 bytes of RTC backup registers
- 4 Kbytes of backup SRAM
- The LSE oscillator
- PC13 to PC15 I/Os, plus PI8 I/O (when available)

To retain the content of these blocks when VDD is turned off, the V<sub>BAT</sub> pin can be connected to an optional battery providing a standby voltage supply.

The switch to the V<sub>BAT</sub> supply is controlled by the powerdown reset embedded in the Reset block.

After reset, the backup domain (RTC registers, RTC backup register and backup SRAM) is protected against possible unwanted write accesses.



Voltage scaling and Over-drive mode offer flexibility between required performance and consumption. Over-drive mode allows the CPU and core logic to operate at higher frequencies than the normal mode for a given voltage scaling.

In Run mode, three voltage scaling modes are available:

- Voltage scale 1 is the high-performance range, allowing a system clock up to 180 MHz. 216 MHz is possible with Over-drive.
- Voltage scale 2 is the medium-performance range, allowing a system clock up to 168 MHz. 180 MHz is possible with Over-drive.
- Voltage scale 3 is low-performance and low-power range that allows a system clock up to 144 MHz.

### Sleep mode \_\_\_\_\_

#### All peripherals available and fastest wakeup time

- Core is stopped, each peripheral clock can be gated ON or OFF
- Entered from by executing WFI (Wait For Interrupt) or WFE (Wait For Event)
- Two mechanisms to enter this mode
  - Sleep Now: MCU enters Sleep mode as soon as WFI/WFE instruction are executed
  - Sleep on Exit: MCU enters Sleep mode as soon as it exits the lowest priority ISR.
    - The stack is not popped before entering Sleep mode, it will not be pushed when the next interrupt occurs, saving running time
  - Controlled by Cortex-M7 System Control Register [SLEEPONEXIT]



Sleep mode allows all peripherals to be used and features the fastest wakeup time.

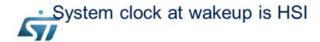
In this mode, the CPU is stopped and each peripheral clock can be configured by software to be gated ON or OFF during the Sleep mode.

This mode is entered by executing the assembler instruction Wait for Interrupt or Wait for Event.

Depending on the SLEEPONEXIT bit configuration in the Cortex-M7 System Control Register, the MCU enters Sleep mode as soon as the instruction is executed, or as soon as it exits the lowest priority interrupt sub-routine. This last configuration saves time and reduces consumption by eliminating the need to pop and push the stack.

#### Lowest power modes with full retention

- SRAM and all peripherals registers retention
  - · Under-drive mode: the 1.2 V domain is preserved in reduced leakage mode
- All high-speed clocks are stopped
- LSE (32.768 kHz external oscillator) and LSI (32 kHz internal oscillator) can be enabled
- EXTI peripheral can wake up from Stop mode
- Wakeup time from 15 to 120 µs



STM32F7 devices feature Stop mode with different configurations to reduce leakage: Stop is the lowest power mode with full retention and only a 15µs wakeup time to Run mode on HSI clock.

The contents of SRAMs and all peripheral registers are preserved in Stop mode.

All high-speed clocks are stopped.

The 32.768 kHz external oscillator and 32 kHz internal oscillator can be enabled.

Some peripherals can be active (RTC, LPTIM). All EXTI lines can wake up from Stop mode.

Wakeup time depends on the power regulator and Flash memory configuration, it can be in the range of 15 up to 120 µs.

The system clock on wake-up is the internal high-speed oscillator running at 16 MHz.

Stop mode with under-drive mode enabled is the lowest

power mode with full retention.

## Standby mode -17

#### Lowest power mode

- Voltage regulator off, the entire VCORE domain is powered off.
- Possibility to retain data in backup SRAM and backup registers
  - · => all registers except those in Backup domain are reset.
  - · => reset generated on the pad
- Wakeup sources: WKUP, RTC, and NRST pin.
- · 6 wakeup pins: the polarity of each of the wakeup pins is configurable
- All GPIOs are in high-impedance state.



Standby mode is the lowest power mode in which the 128-byte backup registers and 4 Kbytes backup SRAM are retained.

The voltage regulator is in Power down mode and the SRAMs and the peripherals registers are lost. As the  $V_{\text{CORE}}$  domain is powered off,

The ultra-low-power brown-out reset is always ON to ensure a safe reset regardless of the VDD slope. I/O are in high-impedance state during Standby mode.

6 wakeup pins are available to wake up the device from Standby mode. The polarity of each wakeup pin is configurable.

The wakeup from Standby generates a system reset. Wakeup time is 313µs, but the software initialization and

configuration have to be taken into account as well.

## VBAT backup domain

#### RTC still running and backup registers preserved in case of VDD loss

- Backup domain contains:
  - RTC clocked by 32.768 kHz LSE oscillator, including tamper pins
  - Backup registers
  - Backup SRAM
  - RCC BDCR register
- Automatic internal switch between VBAT and VDD when VDD is powered down and powered on



The backup domain allows to keep the RTC functional and to preserve the backup registers in case the VDD supply is down, thanks to a backup battery connected to the VBAT pin.

The backup domain contains the RTC clocked by the low-speed external oscillator at 32.768 kHz. 2 tamper pins are functional in VBAT mode, and erase the 128byte backup registers also included in the VBAT domain, in case of intrusion detection.

The backup domain also contains the RTC configuration register.

In case VDD drops below a certain threshold, the backup domain power supply automatically switches to VBAT. When VDD is back to normal, the backup domain power supply automatically switches back to VDD.

# Power consumption figures ==

STM32 mode	STM32F74x/ STM32F75x	STM32F76x/ STM32F77x	Unit	Conditions
Run mode	108	92	mA	Run mode : f <sub>HCLK</sub> = 216 MHz, Coremark executed from Flash, peripherals OFF
Sleep mode	35	18	mA	Sleep mode : $f_{HCLK}$ = 216 MHz, peripherals OFF
Stop mode	100	130	μА	Main regulator in low-voltage and under-drive mode, Flash memory in Deep power-down mode
Standby mode w/o and w/ RTC	2.3 / 2.9	2.4 / 3.5	μА	VDD = 3.3 V, RTC ON and LSE in low-drive mode
VBAT mode w/ RTC	0.72	1.13	μА	



This slide illustrates typical power consumption figures for STM32F7 series.

Typical values measurements conditions are room temperature (25°C) and VDD=3.3V

Dynamic run mode consumption is in the range of 425 µA/MHz, while running CoreMark code from Flash memory at maximum frequency.

Stop low-power mode with full retention for peripheral configuration and SRAMs is in the range of 130  $\mu$ A. For more details, you can refer to the datasheet.

# Option bytes 20

- 2 option bits can be configured in Flash options bytes to prohibit a given low-power mode:
  - nRST\_STDBY: When cleared, a reset is generated when entering Standby mode
  - nRST STOP: When cleared, a reset is generated when entering Stop mode



2 bits are available in the Flash option bytes to prohibit entering a given low-power mode. When cleared, these option bits trigger a reset when entering either Standby or Stop modes. This is a security feature used to reduce the impact of unintentional entry into these low-power modes. In case these low-power modes are not used in user code, the option should be enabled.

## Debug information =21

- 3 bits in DBGMCU\_CR register allows to debug in Sleep, Stop, Standby modes:
  - DBG\_STANDBY: When set, the digital part is not unpowered in Standby mode, and HCLK and FCLK remain ON, provided by an internal RC. In addition, the MCU in under system reset during Standby.
  - DBG\_STOP: When set, HCLK and FCLK remain ON in Stop mode, provided by an internal RC.
  - DBG\_SLEEP: When set, HCLK and FCLK remain ON in Sleep mode.
- When these bits are set, the connection with the debugger is kept during low-power modes. After wakeup, debugging is still possible.



3 bits are available in the Debug Control Register, in order to allow debugging in Sleep, Stop and Standby modes. When the related bit is set, the regulator is kept ON in Standby mode, and the HCLK and FCLK clocks remain ON to keep the debugger active. This maintains the connection with the debugger during the low-power modes, and continues debugging after wakeup. Remember to clear these bits when the MCU is not under debug, because the consumption is higher in those low-power modes when these bits are set, due to the fact they force the clocks and the regulators to remain enabled.